

IGBT - Ultra Field Stop 1200 V, 60 A FGY60T120SQDN

General Description

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Ultra Field Stop Trench construction, and provides superior performance in demanding switching applications, offering both low on-state voltage and minimal switching loss. The IGBT is well suited for UPS and solar applications. Incorporated into the device is a soft and fast co-packaged free wheeling diode with a low forward voltage.

Features

- Extremely Efficient Trench with Field Stop Technology
- Maximum Junction Temperature $T_J = 175$ °C
- Low Saturation Voltage: $V_{CE(sat)} = 1.7 \text{ V (Typ.)} @ I_C = 60 \text{ A}$
- 100% of the Parts Tested for I_{LM} (Note 1)
- Soft Fast Reverse Recovery Diode
- Optimized for High Speed Switching
- RoHS Compliant

Applications

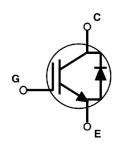
• Solar Inverter, UPS

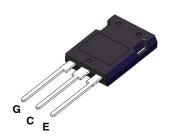
ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Symbol	Description	Value	Unit
V _{CES}	Collector to Emitter Voltage	1200	V
V _{GES}	Gate to Emitter Voltage	±25	V
	Transient Gate to Emitter Voltage	±30	V
I _C	Collector Current @ (T _C = 25°C)	120	Α
	Collector Current @ (T _C = 100°C)	60	Α
I _{LM} (1)	Pulsed Collector Current @ (T _C = 25°C)	240	Α
I _{CM} (2)	Pulsed Collector Current	240	Α
I _F	Diode Forward Current @ (T _C = 25°C)	120	Α
	Diode Forward Current @ (T _C =100°C)	60	Α
I _{FM}	Pulsed Diode Max. Forward Current	240	Α
P _D	Maximum Power Dissipation	F47	W
	@ (T _C = 25°C) @ (T _C =100°C)	517 259	W
TJ	Operating Junction Temperature	-55 to +175	°C
T _{stg}	Storage Temperature Range	-55 to +175	°C
TL	Maximum Lead Temp. For soldering Purposes, 1/8" from case for 5 seconds	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

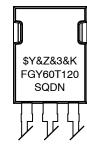
- 1. VCC = 800 V, V_{GE} = 15 V, I_{C} = 240 A, R_{G} = 68 Ω , Inductive Load 2. Repetitive rating: Pulse width limited by max. Junction temperature





Power TO247 (TO-247H03)

MARKING DIAGRAM



&Y = onsemi Logo

&3 = Data Code (Year & Week)

FGY60T120SQDN= Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 3 of this data sheet.

THERMAL CHARACTERISTICS

Symbol	Parameter	FGY60T120SQDN	Unit
R _{θJC} (IGBT)	Thermal Resistance, Junction to Case, Max.	0.29	°C/W
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case, Max.	0.42	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	°C/W

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit	
OFF CHARACTERISTICS							
BV _{CES}	Collector to Emitter Breakdown Voltage	$V_{GE} = 0V$, $I_{C} = 500 \mu A$	1200	-	_	V	
I _{CES}	Collector Cut-Off Current	V _{CE} = V _{CES} , V _{GE} = 0 V	-	-	400	μΑ	
I _{GES}	G-E Leakage Current	V _{GE} = V _{GES} , V _{CE} = 0 V	-	_	±200	nA	
ON CHARAC	TERISTICS						
V _{GE(th)}	G-E Threshold Voltage	$I_C = 400 \mu A, V_{CE} = V_{GE}$	4.5	5.5	6.5	V	
		I _C = 60 A, V _{GE} = 15 V	-	1.7	1.95	V	
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I _C = 60 A _, V _{GE} = 15 V, T _C = 175°C	_	2.3	_	V	
DYNAMIC CH	HARACTERISTICS	<u> </u>	Į.	<u> </u>		<u> </u>	
C _{ies}	Input Capacitance		_	7147	-	pF	
C _{oes}	Output Capacitance	$V_{CE} = 20 \text{ V, } V_{GE} = 0 \text{ V,}$ f = 1 MHz	_	203	-	pF	
C _{res}	Reverse Transfer Capacitance	1 – 1 1911 12	_	114	-	pF	
SWITCHING CHARACTERISTICS							
t _{d(on)}	Turn-On Delay Time	V_{CC} = 600 V, I_{C} = 60 A, R_{G} = 10 Ω , V_{GE} = 15 V, Inductive Load, T_{C} = 25°C	-	52	-	ns	
t _r	Rise Time		_	84	-	ns	
td(off)	Turn-Off Delay Time		_	296	-	ns	
t _f	Fall Time		_	56	-	ns	
Eon	Turn-On Switching Loss		_	5.15	-	mJ	
Eoff	Turn-Off Switching Loss		_	1.82	-	mJ	
Ets	Total Switching Loss		_	6.97	-	mJ	
td(on)	Turn-On Delay Time		_	40	-	ns	
t _r	Rise Time	$V_{CC} = 600 \text{ V}, I_C = 60 \text{ A}, R_G = 10 \Omega,$	_	72	-	ns	
td(off)	Turn-Off Delay Time	$V_{GE} = 15 \text{ V},$	_	324	-	ns	
t _f	Fall Time	Inductive Load, T _C = 175°C	_	144	-	ns	
Eon	Turn-On Switching Loss		_	7.18	-	mJ	
Eoff	Turn-Off Switching Loss		_	3.1	-	mJ	
Ets	Total Switching Loss		_	10.28	-	mJ	
Q_g	Total Gate Charge		-	311	-	nC	
Qge	Gate to Emitter Charge	$V_{CE} = 600 \text{ V}, I_{C} = 60 \text{ A}, V_{GE} = 15 \text{ V}$	-	57	-	nC	
Qgc	Gate to Collector Charge		-	153	-	nC	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ELECTRICAL CHARACTERISTICS OF THE DIODE ($T_C = 25$ °C unless otherwise noted)

Symbol	Parameter	Test Condition		Min.	Тур.	Max.	Unit
.,	Diede Fee aut Valles		T _C = 25°C	-	3.4	4	.,
V _{FM} Diode Forward Voltage	Diode Forward Voltage		T _C = 175°C	-	3.2	-	V
	t _{rr} Diode Reverse Recovery Time		T _C = 25°C	-	91	-	ns
t _{rr}			T _C = 175°C	-	309	-	
Q _{rr} Diode Reverse Recovery Charge	I _F = 60 A	T _C = 25°C	-	860	-	nC	
	Diode Reverse Recovery Charge		T _C = 175°C	-	4902	-	
I _{rrm}	Diode Reverse Recovery Current		T _C = 25°C	_	19	_	А
			T _C = 175°C	-	32	_	

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Quantity
FGY60T120SQDN	FGY60T120SQDN	TO-247-3LD (Pb-Free)	30/Tube

TYPICAL PERFORMANCE CHARACTERISTICS

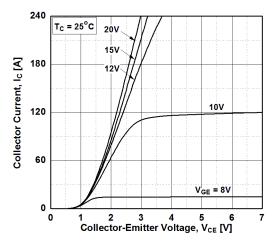


Figure 1. Typical Output Characteristics

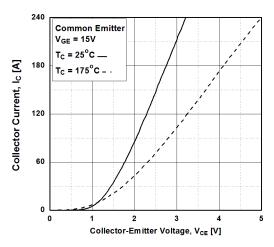


Figure 3. Typical Saturation Voltage Characteristics

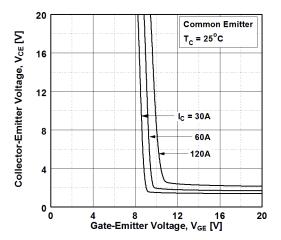


Figure 5. Saturation Voltage vs. V_{GE}

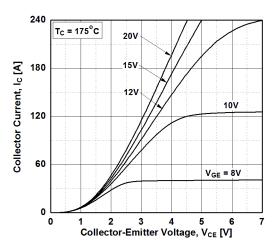


Figure 2. Typical Output Characteristics

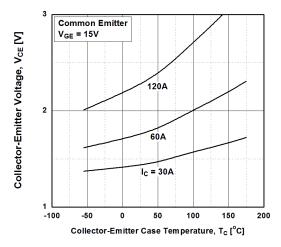


Figure 4. Saturation Voltage vs. Case Temperature at Variant Current Level

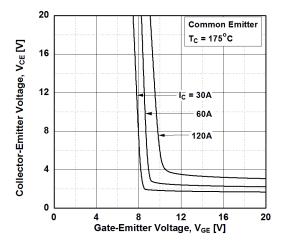


Figure 6. Saturation Voltage vs. V_{GE}

TYPICAL PERFORMANCE CHARACTERISTICS

15

Common Emitter

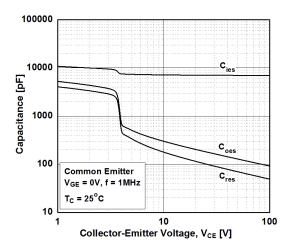
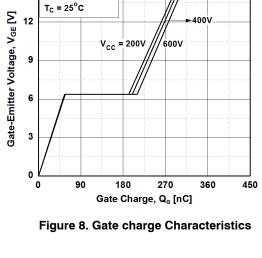


Figure 7. Capacitance Characteristics



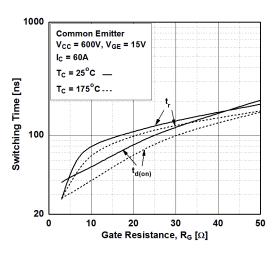


Figure 9. Turn-on Characteristics vs. Gate Resistance

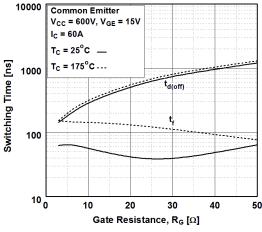


Figure 10. Turn-off Characteristics vs. Gate Resistance

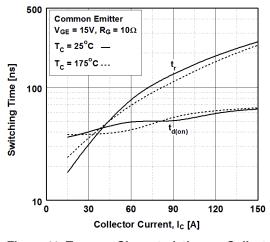


Figure 11. Turn-on Characteristics vs. Collector Current

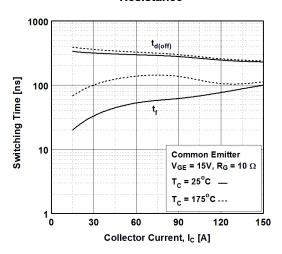


Figure 12. Turn-off Characteristics vs. Collector Current

TYPICAL PERFORMANCE CHARACTERISTICS

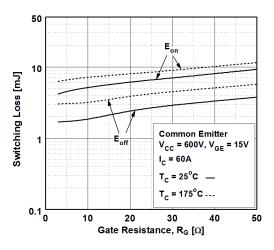


Figure 13. Switching Loss vs. Gate Resistance

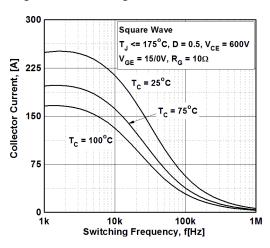


Figure 15. Load Current vs. Frequency

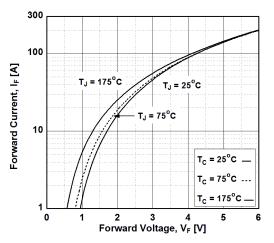


Figure 17. Forward Characteristics

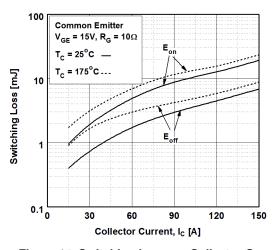


Figure 14. Switching Loss vs. Collector Current

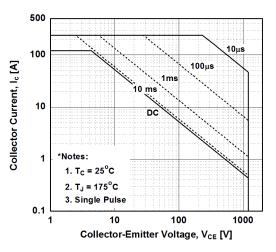


Figure 16. SOA Characteristics

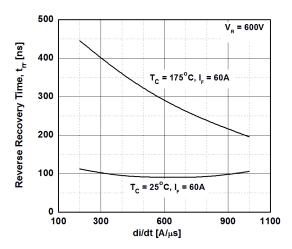
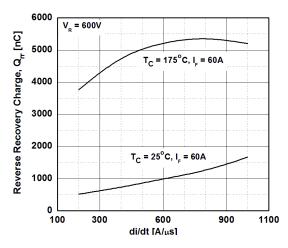


Figure 18. Reverse Recovery Time vs. di_F/dt

TYPICAL PERFORMANCE CHARACTERISTICS



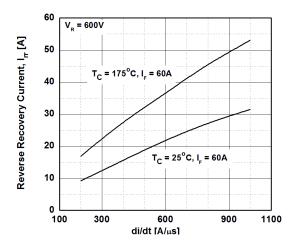


Figure 19. Reverse Recovery Charge vs. di_{F}/dt

Figure 20. Reverse Recovery Current vs. di_F/dt

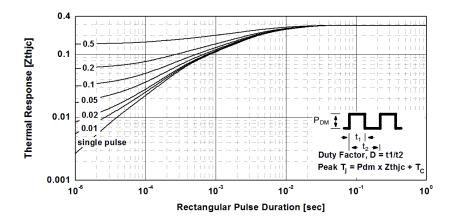


Figure 21. Transient Thermal Impedance if IGBT

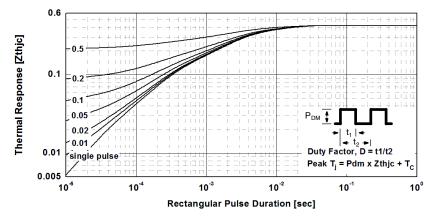


Figure 22. Transient Thermal Impedance if Diode



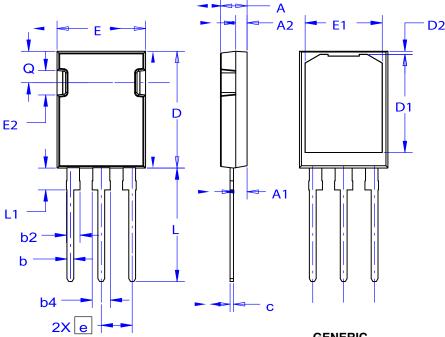


TO-247-3LD CASE 340CD ISSUE A

DATE 18 SEP 2018

NOTES:

- A. THIS PACKAGE DOES NOT CONFORM TO ANY STANDARDS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- D. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.



DIM	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	4.58	4.70	4.82	
A 1	2.20	2.40	2.60	
A2	1.80	2.00	2.20	
D	20.32	20.57	20.82	
Е	15.37	15.62	15.87	
E2	4.12	4.32	4.52	
е	~	5.45	~	
L	19.90	20.00	20.10	
L1	3.69	3.81	3.93	
Q	5.34	5.46	5.58	
b	1.10	1.20	1.30	
b2	2.10	2.24	2.39	
b4	2.87	3.04	3.20	
С	0.51	0.61	0.71	
D1	16.63	16.83	17.03	
D2	0.51	0.93	1.35	
E1	13.40	13.60	13.80	

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON13857G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	TO-247-3LD		PAGE 1 OF 1	

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMI., and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems. or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales